



## Package PLCC84

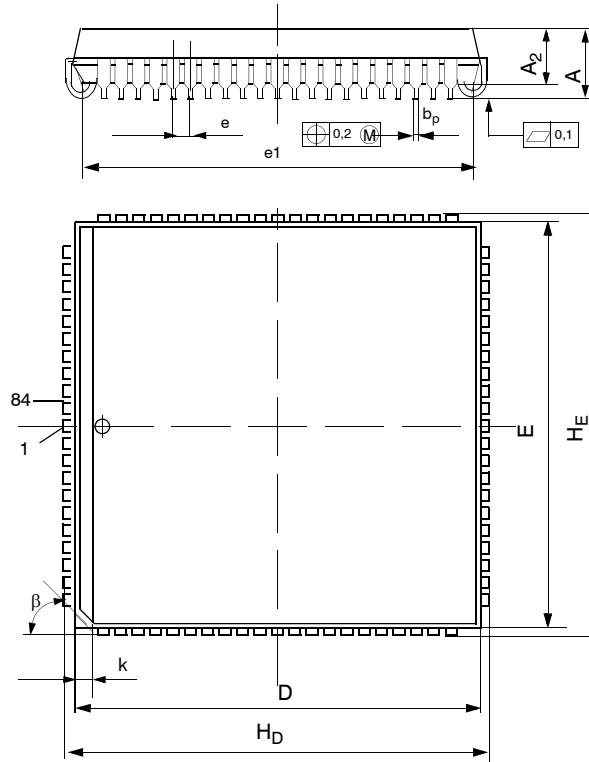
**MDS  
724**

Dimensions in millimetres

Supersedes  
Edition 03.92  
1. Amendment 02.93

Based on IEC 191-2Q: Type 112E13

### 1 Dimensions



Dimensions of Sub-Group B1	
$A_{\max}$	5,10
$b_{P\min}$	0,33
$b_{P\max}$	0,53
$e_{\text{nom}}$	1,27
$H_{D\min}$	30,10
$H_{D\max}$	30,40
$H_{E\min}$	30,10
$H_{E\max}$	30,40

Dimensions of Sub-Group C1	
$A_{\min}$	4,19
$A_{2\min}$	3,10
$A_{2\max}$	3,91
$D_{\min}$	29,13
$D_{\max}$	29,41
$E_{\min}$	29,13
$E_{\max}$	29,41
$k_{\min}$	1,00
$\beta$	45°
$e_{1\min}$	27,68
$e_{1\max}$	28,70

- 2 Weight**  $\leq 6,9$  g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** J-bends

Zentrum Mikroelektronik Dresden AG		
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